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a printed circuit board covering the entire first layer and having an opposing surface provided opposite the face of the piezoelectric substrate with the first layer disposed between said opposing surface and said face, said opposing surface having an area equal to an area of said face of said piezoelectric substrate, said printed circuit board further having external conductive contacts; and

conductive via holes going through the first layer and the printed circuit board and connecting the internal and external conductive contacts.

2. (Amended) The surface acoustic wave component according to claim 1, wherein the first layer is made of photosensitive resin.

3. (Amended) The surface acoustic wave component according to claim 1 or 2, comprising a second layer, called an adhesive layer, located between the first layer and the printed circuit board.

4. (Amended) The surface acoustic wave component according to claim 1 or 2, wherein an external face of the piezoelectric substrate and side faces of the component are covered with a third layer that is hermetic.

5. (Amended) The surface acoustic wave component according to claim 1 or 2, wherein the printed circuit board is metallized on a surface opposite to the first layer.

6. (Amended) The surface acoustic wave component according to claim 1 or 2, wherein the first layer has acoustic absorbent properties.

#### REMARKS

Favorable reconsideration of this application as presently amended and in light of the following discussion is respectfully requested.